

Title (en)

Insole comprising an electronic chip

Title (de)

Einlegesohle, der einen elektronischen Chip umfasst

Title (fr)

Semelle intérieure comportant une puce électronique

Publication

**EP 2392220 A1 20111207 (EN)**

Application

**EP 10005748 A 20100602**

Priority

EP 10005748 A 20100602

Abstract (en)

The present invention relates to an innersole (1), in particular for a sports shoe, and shoe comprising an electronic chip (2). In order to provide a shoe, in particular a sports shoe, with an electronic chip in a more cost efficient way compared to the prior art, wherein the chip can easily be replaced or removed in case of failure or for recycling, the invention provides an innersole, in particular for a sports shoe, wherein the innersole comprises an electronic chip. It may be fitted into any kinds of shoes and may be readily replaced or removed, as is not an inherent part of the shoe.

IPC 8 full level

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CPC (source: EP)

**A43B 3/34** (2022.01); **A43B 17/00** (2013.01)

Citation (applicant)

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